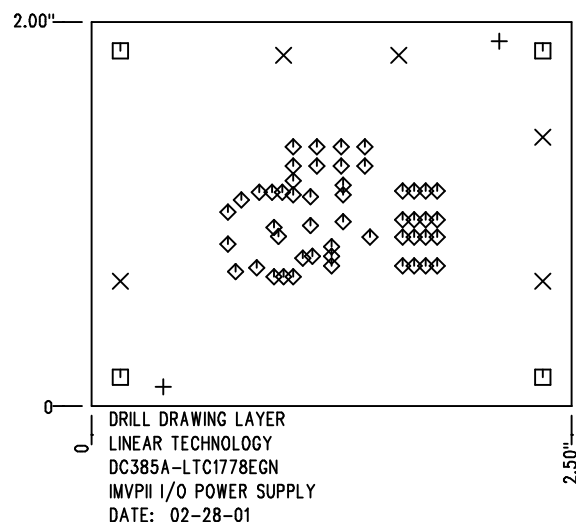


REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		

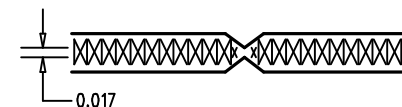


SHOWN FROM COMPONENT SIDE


SIZE	QTY	SYM	PLTD
70	2	+	NPLTD
94	5	×	PLTD
125	4	□	PLTD
20	50	◇	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE READ ME FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
DRAWN	INT	DATE		
CHECK			TITLE: Fabrication Drawing IMVPII I/O POWER SUPPLY	
DESIGN	KIM T.	02-28-01		
ENGR	GORAN P.	02-28-01	SIZE A DEMO DC385A-1*LTC1778EGN REV. A	
SCALE = NONE				
DES- 0000			SHT 1 of 1	